

IN THE SPECIFICATION

Page 1, line 1, before "BACKGROUND OF THE INVENTION"
please insert the following section heading and paragraph:

--CROSS REFERENCE TO RELATED APPLICATIONS

This application claims the benefit and is a
divisional of Application No. 09/665,034, filed
September 9, 2000, now pending which is a
continuation of Application No. 09/153,630, filed
September 15, 1998, now issued as U.S. Patent No.
6,153,829.--

Page 6, line 18, please amend the paragraph beginning
there at as follows:

"The bond pads 16 of the first bond shelf 18 [20] are
connected to a pair of power busses 24 and 26 within the
package. The busses 24 and 26 are separated and located
within the same horizontal plane of the package. By
locating both power busses 24 and 26 within the same plane
the present invention provides a package that may require
less layers than a package that has two power busses located
within different layers of the package."

Page 7, line 23, please amend the paragraph beginning
there at as follows:

"The bond pads 16[, contacts 32] and layers of busses
24 [,] and 26, routing traces 28, bus 30, and contacts 32
may all be interconnected by vias 38. The busses 24 and 26
may include clearance spaces 42 that electrically isolate
the busses 24 and 26 from the vias 38. Additionally, the
busses 24 and 26 are also separated by spaces 43."

Page 8, line 1, please amend the paragraph beginning
there at as follows:

"Figure 4 shows a first conductive strip 44 and a second conductive strip 46 that wrap around an edge of the first bond shelf 18 [20] to connect the bond pads 16 to the power busses 24 and 26. The conductive strips 44 and 46 can be separated by a pair of notches 48 formed in the first bond shelf 18 [20]. Some of the bond pads 16 are connected [by strip 44] to bus 24 by conductive strip 44 while other bond pads 16 are connected to bus 26 by strip 46. The separate strips allow the bond pads 16 on the first bond shelf 18 to be connected to two different voltage levels. The other bond pads 16 on the first bond shelf 18 may be [20 are] interconnected to other layers and/or contacts 32 [34] by vias 38."

Page 8, line 24, please amend the paragraph beginning there at and continuing over to page 9 as follows:

"The conductive strips 44 and 46 can be formed by initially masking off all surfaces of the package housing, except the edge 49 of the [third shelf 22] first bond shelf 18 with a plating resist maskant 50, as shown in Figure 5. The masked housing can then be dipped into a plating bath 52 as shown in Figure 5 6. The plating bath 52 plates a conductive material such as copper onto the edge 49 of the first bond shelf 18. The maskant 50 is then removed and the notches 48 can be drilled into the edges of the first bond shelf 18 to separate the plated material into the first and second conductive strips 44 and 46. All exposed copper surfaces may then be plated with gold."

Page 9, line 9, please amend the paragraph beginning there at as follows:

"As shown in Figure 7, portions 54 of the conductive strips 44 and 46 may extend onto the first bond shelf 18 to

connect to a bonding pad 16. The extra portions 54 may further anchor the conductive strips 44 and 46 to the housing and reduce the likelihood of delamination during the drilling process. The additional portions 54 can be formed by not masking the end of the first bond shelf 18 so that conductive material plates onto the shelf."